



Type Document	Product Specification	Revised /Edition	N
Date Issued	2003/10/20	Data Revised	2020/12/18
Subject : JS-5001 JS-5001-T JS-5001-TA/TPA JS-4001 JS-4001R Pitch : 3.96mm Wire to Board Power Connector Series.			Issued By: Engineering Dept.

*This specification is referred to 3.96mm DIP series wire to board connector.*

*本規格書內容係提供 3.96 mm DIP 系列產品相關參考，*

*其用途為電線端相接於電路板端動力電源連接器*

## -INDEX-

- 1.0 Product Name/Part Number & Drawing Number.(產品名稱 / 產品型號及圖面型號)
- 2.0 Construction/Dimensions/Material & Surface Finish.(材質以及表面鍍層)
- 3.0 Characteristic.(產品特性)
- 4.0 Specimen.(樣本圖示)
- 5.0 Applicable Standards.(適用規範)
- 6.0 Mechanical Performance.(機械性能)
- 7.0 Electrical Performance.(電氣性能)
- 8.0 Environmental Performance.(環境性能)
- 9.0 Remark (備註).

REV. (版次)	Revision Record (改版變更原因)	Date(日期)	ECN No
H	1.增加耐久性測試 2.刪除硫化氫 3.修正(EIA-364) 參考規範 4. 依安規認證增列額定電壓 5.增列 AWG 與額定電流對照 6. 修改 Insertion & Withdrawal Force 並區分單接觸點與三接觸點兩種規格 7. Crimp Terminal Retention Force 原規格 3.0kgf/Min.修改為 3.6kgf/Min.	2012/05/28	EC2012-05-014
I	增加2.0項 . 塑料66 UL94V-0 +GF(Halogen Free)及8.9 項. 焊錫耐熱溫度	2011/01/13	EC2011-01-013
J	1 增訂Wave Peak Soldering In- Process Temperature Profile 2.修訂Solder Ability 附註Tin Plated : 95% / Gold Plated : 75% 3.修訂Wire Pullout Force(Axial)規格值	2013/12/09	EC2013-12-009
K	1 增訂 8.7 項 Cold(Low Temperature)耐寒試驗 , EIA-364-59A 2 增訂 3.5 項 Storage of Package 以及 3.6 項 Floor Life 3 撤銷 2.0 項 塑料 66 UL94V-0 +GF(Halogen Free)	2014/07/10	EC2014-07-010
L	1.修訂Wave Peak Soldering In- Process Temperature Profile 2.增訂4.0項 66V0 Photograph	2014/10/13	EC2014-10-013
M	1 增訂 8.8 項 Salt Spray 鹽水噴霧 2 修正 8.9 項 Solder Ability 焊錫性 3.刪除 BSI 標示	2017/06/07	EC2017-06-007
N	Delete 8.10.1.2 溫度曲線圖	2020/12/18	EC2020-12-012



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**1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):**

Product Name(產品名稱)		Part Number(產品型號)	Drawing Number(圖面型號)
Crimp Terminal (3 Point of Contacts)		JS-5001-TA ; JS-5001-TPA	
Crimp Terminal (1 Point of Contacts)		JS-5001-T	
Housing		JS-5001	
Wafer	Straight (直立式)	JS-4001-XX(XXX) ; JS-4001-XXS(XXX)	
		JS-4001-XX(V0X) ; JS-4001-XXS(V0X)	
	Right Angle (臥式)	JS-4001R-XX(XXX)	

Note: (XX) -> The number of the circuits, (XXX) -> Fill in special options (Refer the drawing).

**2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):**

Part Name(零件名稱)		Material(材質)	Surface Finish(表面鍍層)
Crimp Terminal (柳壓端子)	(1 Point of Contacts 單點接觸)	Brass	先電鍍後沖壓 Stamping after tin plated
	(3 Point of Contacts 三點接觸)		先衝壓後電鍍 Stamping Before tin-Plated
Housing(電線端連接器)		Nylon 66	UL 94V-2
Wafer (電路板端連接器)	Normal Square Pin (標準方型導體)	Brass	Tin-Plated or Gold Plated
	Square Pin with Holding Construction (具有增加拔出力結構的方型導體)		
	Base(膠座)	Nylon 66	UL 94V-2 UL 94V-0

**3.0 Characteristic(產品特性):**

Item(項目)		Standard(標準規範)					
3.1	額定電流 Rated Current	Conductor	AWG	18#	20#	22#	24#
			Area(mm <sup>2</sup> )	0.865 mm <sup>2</sup>	0.534 mm <sup>2</sup>	0.342 mm <sup>2</sup>	0.220 mm <sup>2</sup>
		Size	Amp AC/DC	7 A	5 A	3 A	2 A
3.2	額定電壓 Rated Voltage	250 V AC/DC					
3.3	Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度與濕度範圍) Operating Temp. : -25°C~+85°C ; 85% R.H. Max. Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C 以下溫昇)					
3.4	Applicable Wire 適用電線	3.4.1	(金屬導體型號) Conductor Construction Size: AWG #18~#24				
		3.4.2	(電線絕緣材質外徑) Wire Insulation O.D.: 1.30mm~2.50mm				
3.5	Storage of Package 包裝未拆封之保存	Temperature and Humidity Condition 溫濕度條件			Temperature 溫度 : -10°C~+40°C Percentage Humidity 相對濕度 : 70 % Max		
		Term 保存期限	Housing		2 Years		
			Crimp Terminal & Wafer		1 Year		



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<b>3.6</b>	<b>Floor Life 拆封後使用期限</b>	<b>Crimp Terminal &amp; Wafer</b>	<b>3 Months</b>
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Note: 適用電路板厚度 Applicable Printed Circuit Board Thickness: 1.6 mm

4.0 Specimen(樣本圖示) :

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
Housing JS-5001		Crimp Terminal (1 Point Contact) JS-5001-T	
Wafer Right Angle JS-4001R		Crimp Terminal (3 Point Contact) JS-5001-TA/TPA	
Wafer Straight JS-4001		Wafer Straight JS-4001-XX(V0)	

5.0 Applicable Standards(適用規範):

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors. 電子連接器 適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1 Insertion & Withdrawal Force 嵌入力與拔出力 (JS-5001-T)	Per circuit when mated to a 1.14mm square pin. Insert and withdraw with connectors at the speed rate of 25.4± 3 mm/minute. <b>( Excluding Friction Lock 不包含膠座卡榫結合力 )</b> 連接器兩端勘合以 1.14 mm 方型導體作互配之一端，依每一分鐘 25.4 ± 3 mm 的速率，作嵌入與拔出往返測試 (EIA/ECA 364-13D)	單一接觸點插入力最大容許值 Per contact insertion force : <b>0.96 kgf/Max.</b> 單一接觸點拔出出力最小容許值 Per contact withdrawal force : <b>0.18 kgf/Min.</b>



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Item(項目)		Test Condition(測試條件)	Requirement(規格)
6.2	<b>Insertion &amp; Withdrawal Force</b> 嵌入力與拔出力 (JS-5001-TA/TPA)	Per circuit when mated to a 1.14mm square pin. Insert and withdraw with connectors at the speed rate of 25.4± 3 mm/minute. <b>(Excluding Friction Lock 不包含膠座卡榫結合)</b> 連接器兩端配合以 1.14 mm 方型導體作互配之一端，依每一分鐘 25.4 ± 3 mm 的速率，作嵌入與拔出往返測試 (EIA/ECA 364-13D)	單一接觸點插入力最大容許值 <b>Per contact insertion force : 1.02 kgf/Max.</b> 單一接觸點拔出力最小容許值 <b>Per contact withdrawal force :0.37 kgf/Min.</b>
6.3	<b>Wire Pullout Force(Axial)</b> 電線脫離端子包覆之拔出力(軸向)	Pull out the cable from with contact terminal at the speed rate of 25.4± 3mm/minute. 對端子所包覆電線，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力 (EIA 364-08B )	<b>AWG#18 size wire 9.0kgf/Min.(89N 牛頓)</b>
			<b>AWG#20 size wire 6.7kgf/Min.(66N 牛頓)</b>
			<b>AWG#22 size wire 5.4kgf/Min.(53N 牛頓)</b>
			<b>AWG#24 size wire 3.57kgf/Min.(35N 牛頓)</b>
6.4	<b>Crimp Terminal Retention Force</b> ( in Housing ) 柳線端子與膠座之間 保持力	Axial pull out force on the terminal in the housing at the speed rate of 25.4 ± 3 mm per minute. (EIA 364-05 ) 對於已經存在於膠座當中柳線端子，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力	單一接觸點 Per Contact 最小容許值 <b>3.6kgf/Min.</b>
6.5	<b>Square Pin Retention Force( in Base )</b> 方型導體與膠座之間保持力	Axial pullout force on the square pin in the base at the speed rate of 25.4 ± 3 mm per minute prior to wave solder process 未經波峰焊之前，對於已經存在於膠座當中方型導體，施以每一分鐘 25.4 ± 3mm 速率之軸向拔出力 (EIA/ECA 364-29C )	單一接觸點 Per Contact 最小容許值 <b>2.0kgf/Min.</b>

**7.0 Electrical Performance(電氣性能) :**

Item(項目)		Test Condition(測試條件)	Requirement(規格)
7.1	<b>Contact Resistance</b> (Low –Signal Level) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 100mA are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 100mA (EIA/ECA 364-23C) ( Does not include wire resistance 不包含電線阻抗 )	<b>Contact Resistance: 20 milliohms Max.</b> 最大容許值. 20 毫歐姆
7.2	<b>Insulation Resistance</b> 絕緣阻抗	Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)	<b>Insulation Resistance: Initial 1000megohms Min</b> 最初容許值. 1000 兆歐姆



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.3 Withstanding Voltage 耐電壓	Apply <b>1500A/C (rms)</b> for 1 minute and the leakage current shall not exceed <b>0.5mA</b> to the adjacent terminal and ground of the mate connectors. 對組合狀態下連接器，於其相鄰兩導體末端各施以電 <b>1500A/C(實效值)</b> 時間 1 分鐘，且漏電流必須小於 <b>0.5mA(毫安培)</b> (EIA 364-20C)	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Durability 耐久性	Mate Connectors up <b>25 Cycles</b> at a Maximun rate of <b>10 cycles</b> Per minute prior to environmental test (EIA/ECA 364-09C ) 以組合狀態下連接器且未經環境測試，依每分鐘內進行 <b>10</b> 次嵌入與拔出之最大速率，連續 <b>25</b> 次嵌入與拔出往返測試	(After the test) Contact resistance : <b>40 mΩ Max</b> 經耐久性試驗後接觸阻抗： 最大容許值 <b>40 毫歐姆</b>
8.2 Temperature Rise (Via Current Cycling) 溫度上昇 (經由電流循環操作)	Mate connector . measure the temperature rise of contact when the maximum rated current is passed 以組合狀態下連接器，通過最大容許電流量測其導體溫度上昇值 (EIA 364-70B Conditions 1 . Method 1)	Mate connectors <b>Temperature Rise:</b> <b>+30°C/Max.</b> 組合狀態下之連接器溫度上昇 最大容許值 <b>+30°C</b>
8.3 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 (EIA/ECA 364-28E-Condition I ) Frequency(頻率) : 10~55~10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction.(每一軸向持續 2 小時)	Initial Contact Resistance : <b>20 milliohms Max.</b> 接觸阻抗最初容許值 <b>20 毫歐姆</b> (After the test) Contact Resistance: <b>40 milliohms Max.</b> 經耐振動試驗後接觸阻抗： 最大容許值 <b>40 毫歐姆</b> No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於 <b>1</b> 微秒



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Item(項目)		Test Condition(測試條件)	Requirement(規格)
8.4	Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA 364-31B Conditions III . Method A)</p> <p>以組合狀態下連接器放置於恆定溫度與濕度的空間，依照隨附如下規格要求，進行恆溫恆濕試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C.</p> <p>Relative Humidity(相對濕度) : 90%~95% (RH).</p> <p>Period(週期) : 96 hours continuously. (持續 96 小時)</p>	<p>(After the test)</p> <p>Contact Resistance:</p> <p><b>40milliohms Max.</b></p> <p>經恆溫恆濕試驗後接觸阻抗： 最大容許值. 40 毫歐姆</p>
			<p>(After the test)</p> <p>Insulation Resistance :</p> <p><b>500Megohms Min.</b></p> <p>經恆溫恆濕試驗後絕緣阻抗： 最小容許值. 500 兆歐姆</p>
			<p>經恆溫恆濕試驗後耐電壓：</p> <p>(After the test)</p> <p>Withstanding Voltage:</p> <p><b>1500V A/C for 1 minute</b></p>
8.5	Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I . Method A)</p> <p>One Cycle Consists Of:</p> <p><b>-55°C+0/-3°C for 30 minutes. → Room Temp. 5 minutes</b></p> <p><b>85°C+3/-0°C for 30 minutes. → Room Temp. 5 minutes</b></p> <p>Total Cycles: 5 Cycles.</p> <p>以-55°C +0/-3°C 溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85°C +3/-0°C 溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p>	<p>Same as paragraph 8.4</p> <p>同 8.4 章節</p>



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.6 Thermal Aging 高溫老化試驗	A mated connector shall be placed in a heat oven of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。(EIA 364-17B Conditions III . Method A ) Temperature(溫度) : 85±2°C. Period(週期): 96 hours continuously . (持續 96 小時)	Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值 20 毫歐姆 (After the test) Contact Resistance : 40 milliohms Max. . 經高溫老化試驗後接觸阻抗： 最大容許值.40 毫歐姆
8.7 Cold 耐寒試驗 (Low Temperature)	A mated connector shall be placed in a cold chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於低溫空間內，依照隨附如下規格要求，進行耐寒試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。(EIA 364-59A Procedure 4) Temperature(溫度) : -25±3°C. Period(週期): 96 hours continuously . (持續 96 小時)	Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值 20 毫歐姆 (After the test) Contact Resistance : 40 milliohms Max. . 經耐寒試驗後接觸阻抗： 最大容許值. 40 毫歐姆
8.8 Salt Spray 鹽水噴霧	A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。(EIA 364-26B Conditions B) Density(鹽水密度): 5 % in weight. emperature(溫度): 35±2°C. Period(週期): Terminal or contact (Stamping after tin plated for 8 hours ) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體 (先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時) Salt spray test only define the plating area,without plating area (as copper cross section) will not be defined. 鹽水噴霧測試只判定電鍍區域,無電鍍區域(如折斷面裸銅)則不做判定	Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值:20 毫歐姆 (After the test) Contact Resistance: 40 milliohms Max. 經鹽水噴霧試驗後接觸阻抗： 最大容許值. 40 毫歐姆



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<b>Type Document</b>	<b>Product Specification</b>	<b>Revised /Edition</b>	<b>N</b>
<b>Date Issued</b>	<b>2003/10/20</b>	<b>Data Revised</b>	<b>2020/12/18</b>
<b>Subject : JS-5001 JS-5001-T JS-5001-TA/TPA JS-4001 JS-4001R</b>			<b>Issued By:</b> <b>Engineering Dept.</b>
<b>Pitch : 3.96mm Wire to Board Power Connector Series.</b>			

Item(項目)		Test Condition(測試條件)	Requirement(規格)
8.9	<b>Solder Ability</b> 焊錫性	<p>Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗</p> <p>(EIA 364-52B)</p> <p>Solder Temperature (焊錫溫度) : <b>245 ± 5°C</b></p> <p>Immersion Period (沉浸週期) : <b>3±0.5 Seconds</b></p> <p>(操作方式) : 零件焊錫位置，距離導體末端 <b>1.5mm</b></p> <p>Method : <b>1.5mm from square pin tip</b></p>	<p>Solder entirely <b>95%</b> of immersed area must show no voids or pinholes.</p> <p>焊料覆蓋面積必須達到 <b>95%</b>，而且不能產生氣孔或空隙</p>
8.10	<b>Resistance to Soldering Heat</b> 焊錫耐熱性	<p>Resistance to soldering heat 能夠承受焊錫耐熱範圍 :</p> <p>Refer to Temperature Profile 請參考 <b>8.10.1.1</b> 溫度曲線圖</p> <hr/> <p>by soldering iron 手工烙鐵焊錫適用溫度範圍 :</p> <p><b>350 ± 5°C 3±0.5 Seconds.</b></p> <p>(操作方式) : 零件焊錫位置，距離導體末端 <b>1.5mm</b></p> <p>Method : <b>1.5mm from square pin tip</b></p> <p>(EIA/ECA 364-56C Procedure 3. Conditions A)</p>	<p>No deformation or damage.</p> <p>不可有變形或損壞</p>

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求





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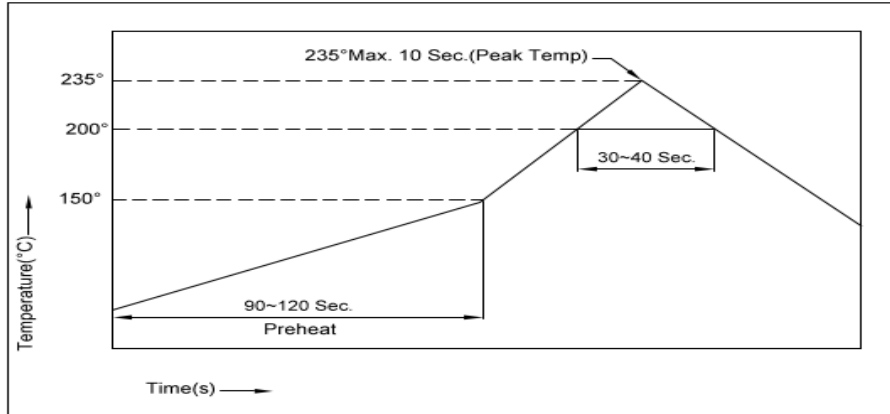
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**8.10.1 Temperature Profile(溫度曲線圖) :**

**8.10.1.1 Wave Peak Soldering In-Lead Free Process 波峰焊無鉛制程**



**9.0 Remark(備註) : Any change or revision for the product specification will not be announced in advance.**

**Please contact our sales representative for the latest information.**

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊。

**Reviewed:** Tom Shih **Approved:** Tom Shih **Verified:** Erin Chou